

AW-CM276NF

**IEEE 802.11 2X2 MU-MIMO ac/a/b/g/n
Wireless LAN + Bluetooth 5.0
NGFF Module**

Datasheet

Version 1.4

Document release	Date	Modification	Initials	Approved
Version0.1	2016/03/02	Initial version	Renton Tao	Daniel Lee
Version0.2	2016/06/06	<ol style="list-style-type: none"> 1. Update Block diagram 2. Update pin definition 3. Update mechanical drawing 	Renton Tao	Daniel Lee
Version0.3	2016/09/12	<ol style="list-style-type: none"> 1. Update pin map 2. Add pin out drawing 3. Remove G17 and G18 	Renton Tao	Daniel Lee
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Version0.5	2016/12/6	<ol style="list-style-type: none"> 1. Update Specifications Table 2. Configuration pins 3. shipping information 	Renton Tao	Daniel Lee
Version0.6	2017/1/13	<ol style="list-style-type: none"> 1. Update BDR power 2. Update pin definitions. 	Renton Tao	Daniel Lee
Version0.7	2017/2/13	Update ESD test conditions	Renton Tao	Daniel Lee
Version0.8	2017/3/2	Update Operating conditions	Renton Tao	Daniel Lee
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Version1.0	2018/02/21	Update BT 4.2 to BT5.0	Renton Tao	Daniel Lee
Version1.1	2018/06/21	Update output power table	Renton Tao	NC Chen
Version1.2	2018/08/2	Revise output power table	Renton Tao	NC Chen
Version1.3	2018/08/7	Update <ol style="list-style-type: none"> 1-3. Key feature 1-4. Specifications Table 	Renton Tao	NC Chen

Version1.4	2019/07/10	Update 4. Pin Definition	Renton Tao	NC Chen
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1. General Description

1-1. Product Overview and Functional Description

HAI ROBOTICS introduces the IEEE 802.11ac/a/b/g/n 2X2 MU-MIMO WLAN & Bluetooth NGFF module --- **AW-CM276NF**. The module is targeted to mobile devices including **Notebook, TV, Tablet and Gaming Device** which need small package module, low power consumption, multiple interfaces and OS support. By using AW-CM276NF, the customers can easily enable the Wi-Fi, and BT embedded applications with the benefits of **high design flexibility, short development cycle, and quick time-to-market**.

Compliance with the IEEE 802.11ac/a/b/g/n standard supporting 802.11ac Wave 2, the AW-CM276NF uses Direct Sequence Spread Spectrum (**DSSS**), Orthogonal Frequency Division Multiplexing (**OFDM**), **DBPSK, DQPSK, CCK** and **QAM** baseband modulation technologies. A high level of integration and full implementation of the power management functions specified in the IEEE 802.11 standard minimize the system power requirements by using AW-CM276NF. In addition to the support of **WPA/WPA2** and **WEP** 64-bit and 128-bit encryption, the AW-CM276NF also supports the **IEEE 802.11i** security standard through the implementation of **Advanced Encryption Standard (AES)/Counter Mode CBC-MAC Protocol (CCMP)**, Wired Equivalent Privacy (**WEP**) with Temporal Key Integrity Protocol (**TKIP**), Advanced Encryption Standard (**AES**)/Cipher-Based Message Authentication Code (**CMAC**), and WLAN Authentication and Privacy Infrastructure (**WAPI**) security mechanisms.

For the video, voice and multimedia applications the AW-CM276NF support **802.11e Quality of Service (QoS)**. The device also supports **802.11h Dynamic Frequency Selection (DFS)** for detecting radar pulses when operating in the 5GHz range.

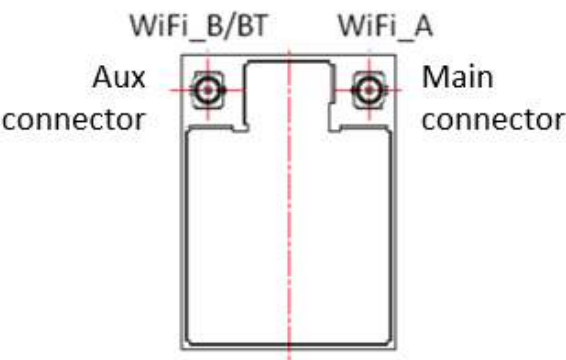
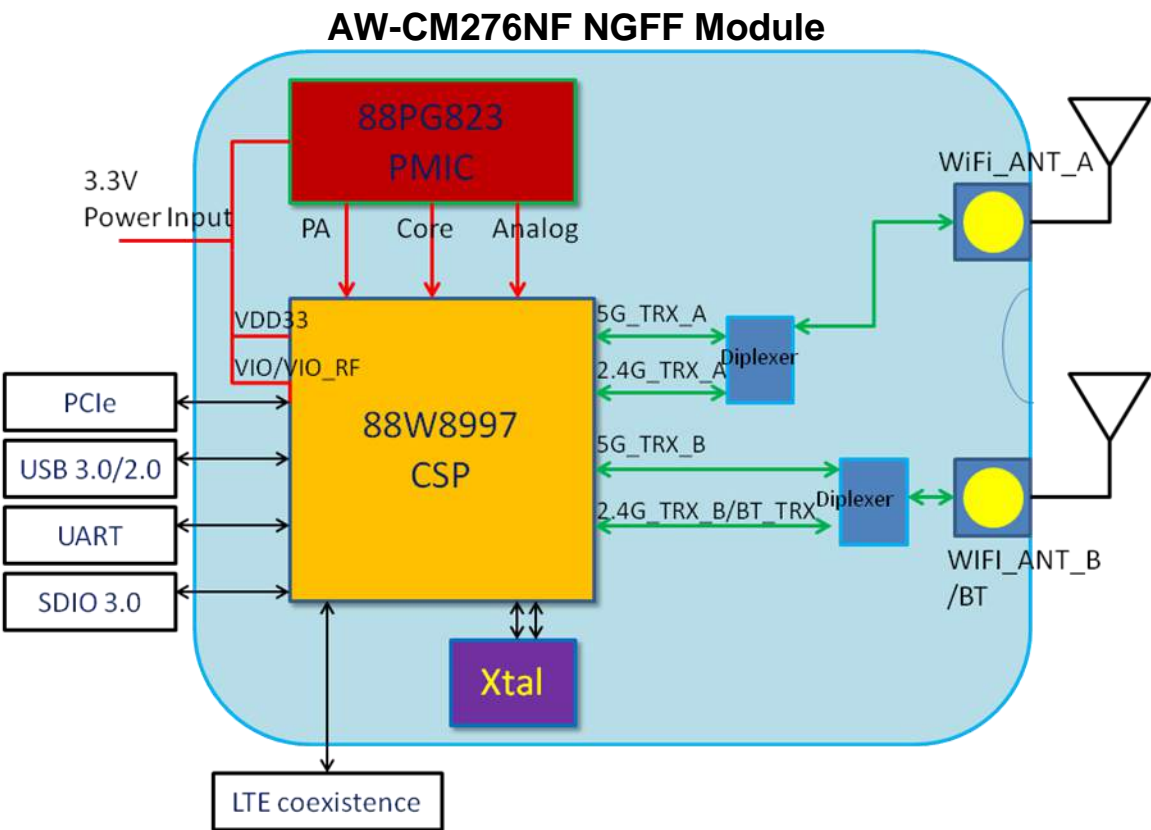
For Bluetooth operation, AW-CM276NF is **Bluetooth 5.0 (supports Low Energy)**.

AW-CM276NF supports **PCIE, USB 3.0/2.0**, and high speed **UART interfaces** for WLAN and Bluetooth to the host processor.

AW-CM276NF is suitable for multiple mobile processors for different applications with the support **cellular phone co-existence**.

AW-CM276NF module adopts Marvell's latest highly-integrated dual-band WLAN & Bluetooth SoC--- **88W8997**. All the other components are implemented by all means to reach the mechanical specification required.

1-2. Block Diagram



Module antenna configuration

1-3. Key feature:

- **PCIe M.2 TYPE 1216: 16mm(L) x 12mm(W) x 1.85 mm(H)(Max)**
- **SDIO 3.0, PCIe, USB 3.0/2.0 interfaces support for WLAN**
- **USB 3.0/2.0, UART interfaces support for Bluetooth**
- **High speed UART,PCM interfaces**
- **Bluetooth 5.0 complaint with Bluetooth 2.1 + Enhanced Data Rate (EDR)**
- **Audio Codec interface support**
- **Sub-meter accuracy WiFi indoor locationing(802.11mc)**
- **Multiple power saving modes for low power consumption**
- **IEEE 802.11i for advanced security**
- **Quality of Service (QoS) support for multimedia applications**
- **Support China WAPI**
- **Lead-free design**
- **Support optional VIO level(default 1.8V)**

1-4. Specifications Table

Model Name	AW-CM276NF			
Product Description	2x2 MU-MIMO Wireless LAN + Bluetooth Combo Module			
WLAN Standard	IEEE 802.11 ac/a/b/g/n, Wi-Fi compliant			
Bluetooth Standard	Bluetooth 5.0 complaint with Bluetooth 2.1+Enhanced Data Rate (EDR)			
Host Interface	PCIe/SDIO/USB for WLAN, USB/UART for Bluetooth			
Major Chipset	Marvell 88W8997			
Dimension	12mm(W) x 16mm(L) x 1.85mm(H)			
Weight	0.0005 kg			
Package	LGA			
Operating Conditions				
Voltage	3.3V+- 10%			
Temperature	Operating: -30~ 85°C ; Storage: -40~ 125°C			
Electrical Specifications				
Frequency Range	2.4 GHz ISM radio band / 5 GHz Unlicensed National Information Infrastructure (U-NII) band			
Number of Channels	802.11ac(VHT20): 36,40,44,48,52,56,60,64,100,104,108,112,116,120,124,128,132,136,140,149,153,157,161,165 802.11ac(VHT40): 38,46,54,62,102,110,118,126,134,151,159 802.11ac(VHT80): 42,58,106,122,138,155 802.11a: USA-36,40,44,48,52,56,60,64,100,104,108,112,116,120,124,128,132,136,140,149,153,157,161,165 802.11b: USA, Canada and Taiwan – 1~11 Most European Countries – 1~13 802.11g: USA, Canada and Taiwan – 1~11 Most European Countries – 1~13 802.11n(HT20): Channel 1~13(2412~2472) 802.11n(HT40): Channel 1~7(2422~2452)			
Modulation	DSSS, OFDM, DBPSK, DQPSK, CCK, 16-QAM, 64-QAM and 256-QAM for WLAN GFSK (1Mbps), Π/4 DQPSK (2Mbps) and 8DPSK (3Mbps) for Bluetooth			
Output Power	WLAN 2.4GHz band	Min	Typ	Max
	11b 11Mbps@EVM≤35%	15.5	17	18.5
	11g 54Mbps@EVM≤-27dB	14.5	16	17.5
	11n HT20 MCS7@EVM≤-28dB	14.5	16	17.5
	11n HT40 MCS7@EVM≤-28dB	12.5	14	15.5
	Unit:dBm			
	WLAN 5GHz band	Min	Typ	Max
	11a 54Mbps@EVM≤-27dB	11	13	15
	11n HT20 MCS7@EVM≤-28dB	11	13	15
	11n HT40 MCS7@EVM≤-28dB	10	12	14
	11ac VHT20 MCS8@EVM≤-30dB	11	13	15
	11ac VHT40 MCS9@EVM≤-32dB	10	12	14
	11ac VHT80 MCS9@EVM≤-32dB	8	10	12
	Unit:dBm			
	BT	Min	Typ	Max
	BDR/BLE	0	2	4

Antenna Connector	Main Connector: WLAN	Aux Connector: WLAN + BT
Receive Sensitivity	<p>Minimum sensitivity(typ): WLAN 2.4GHz band: 11b 11M: -88dBm 11g 54M: -75dBm 11n MCS7 BW20: -72dBm 11n MCS7 BW40: -69dBm</p> <p>WLAN 5GHz band: 11a 54M: -72dBm 11n BW20 MCS7: -69dBm 11n BW40 MCS7: -68dBm 11ac BW20 MCS8: -65dBm 11ac BW40 MCS9: -63dBm 11ac BW80 MCS9: --60dBm</p> <p>Bluetooth: BDR: -83dBm</p>	
Medium Access Protocol	CSMA/CA with ACK	
Data Rates	<p>WLAN 802.11b: 1, 2, 5.5, 11Mbps 802.11a/g: 6, 9, 12, 18, 24, 36, 48, 54Mbps 802.11n: up to 150Mbps-single 802.11n: up to 300Mbps-2x2 MIMO 802.11ac:up to 192.6Mbps (20MHz channel) 802.11ac:up to 400Mbps (40MHz channel) 802.11ac:up to 866.7Mbps (80MHz channel) Bluetooth Bluetooth 5.0 Bluetooth 2.1+EDR data rates of 1,2, and 3Mbps</p>	
Power Consumption	Please refer to test report.	
Operating Range	<p>Open Space: ~300m ; Indoor: ~100m for WLAN Minimum 10 m indoor for Bluetooth The transmission speed may vary according to the environment)</p>	
Security	<ul style="list-style-type: none"> ◆ WAPI ◆ WEP 64-bit and 128-bit encryption with H/W TKIP processing ◆ WPA/WPA2 (Wi-Fi Protected Access) ◆ AES-CCMP hardware implementation as part of 802.11i security standard 	
ESD test condition	<p>HBM: +-2KV CDM: +-500V</p>	
Operating System Compatibility	Linux(Android), More information please contact Azurewave FAE.	
Co-Existence	Please refer to test report.	

*WiFi /BT power & sensitivity measure @ module out

2. Electrical Characteristic

2-1. Absolute Maximum Ratings

Symbol	Parameter	Condition	Min	Typ	Max	Units
Pin73/ VIO	Host I/O power supply	--	--	1.8	2.2	V
		--	--	2.5	3.0	
		--	--	3.3	4.0	
Pin44/ VIO_SD	SDIO power supply	--	--	1.8	2.2	V
		--	--	3.3	4.0	
Pin4,5,72/ 3.3V	3.3V VBAT input	--	--	3.3	3.63	V
T _{storage}	Storage Temperature		-40		125	°C

2-2. Recommended Operating Conditions

Symbol	Parameter	Condition	Min	Typ	Max	Units
Pin73/ VIO	1.8V/2.5V/3.3V digital I/O power supply	--	1.62	1.8	1.98	V
		--	2.25	2.5	2.75	
		--	2.97	3.3	3.63	
Pin44/ VIO_SD	1.8V/3.3V digital I/O SDIO power supply	--	1.62	1.8	1.98	V
		--	2.97	3.3	3.63	
Pin4,5,72/ 3.3V	3.3V VBAT input	--	2.97	3.3	3.63	V
T _A	Ambient operating temperature	--	-30		85	°C

2-3. Clock Specifications

2-3.1 External Sleep Clock Timing

External Sleep Clock is necessary for two reasons:

1. Auto frequency Detection.

This is where the internal logic will bin the Ref clock source to figure out what is the reference clock frequency is. This is done so no strapping is needed for telling 88W8997 what the ref clock input is.

2. Allow low current modes for BT to enter sleep modes such as sniff modes.

The AW-CM276NF external sleep clock pin is powered from the 3.3V voltage supply.

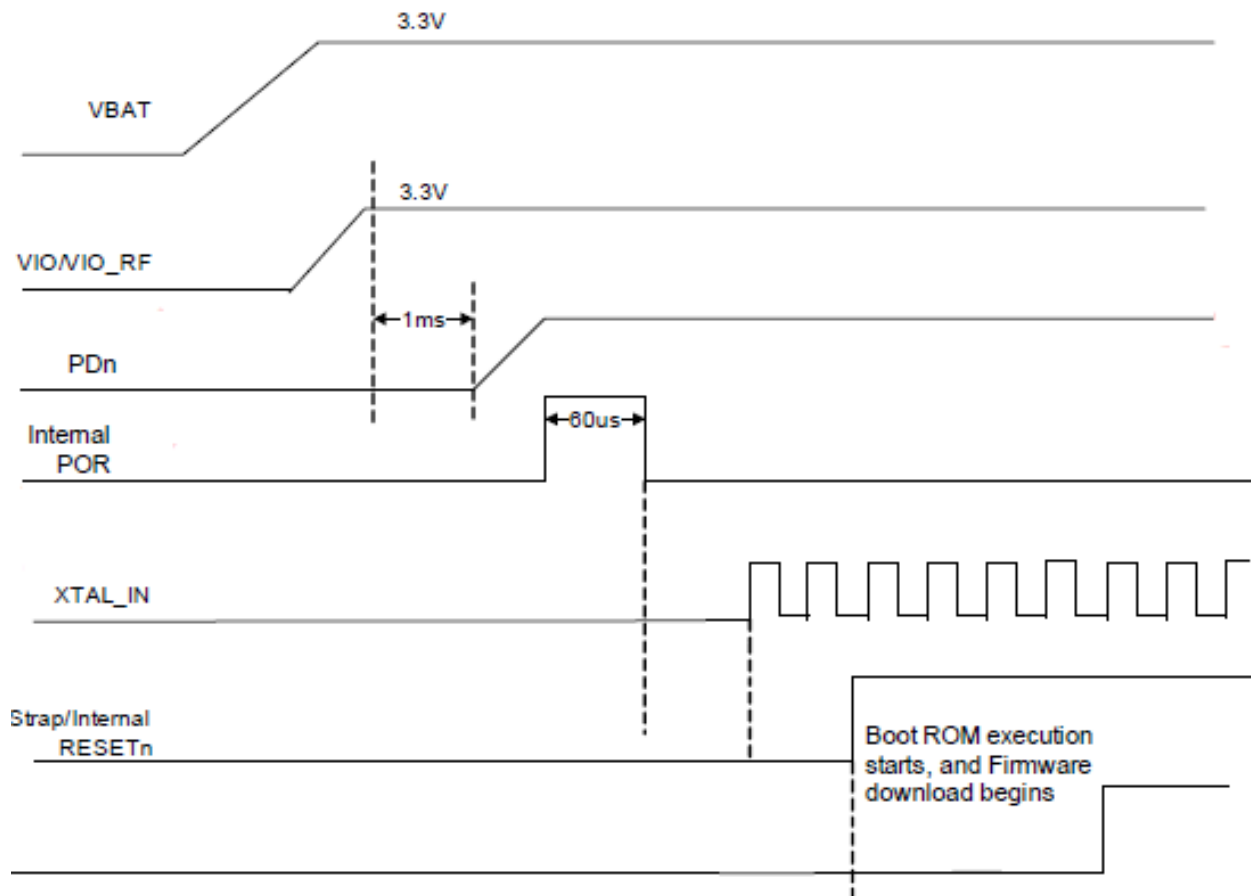
Symbol	Parameter	Min	Typ	Max	Units
CLK	Clock Frequency Range/accuracy +-250ppm(initial, aging, temperature)		32.768		KHz

2-4. Reset Configuration

The AW-CM276NF is reset to its default operating state under the following conditions:

- Power-on reset (POR)
- Software/Firmware reset
- External pin for power down (PDn)

2-5. Power up Timing Sequence



3. Host Interfaces

3-1. SDIO Interface

The AW-CM276NF supports a SDIO device interface that conforms to the industry standard SDIO Full-Speed card specification and allows a host controller using the SDIO bus protocol to access the Wireless module device.

The AW-CM276NF acts as the device on the SDIO bus. The host unit can access registers of the SDIO interface directly and can access shared memory in the device through the use of BARs and a DMA engine.

The SDIO device interface main features include:

Supports SDIO 3.0 Standard

On-chip memory used for CIS

Supports SPI, 1-bit SDIO, and 4-bit SDIO transfer modes

Special interrupt register for information exchange

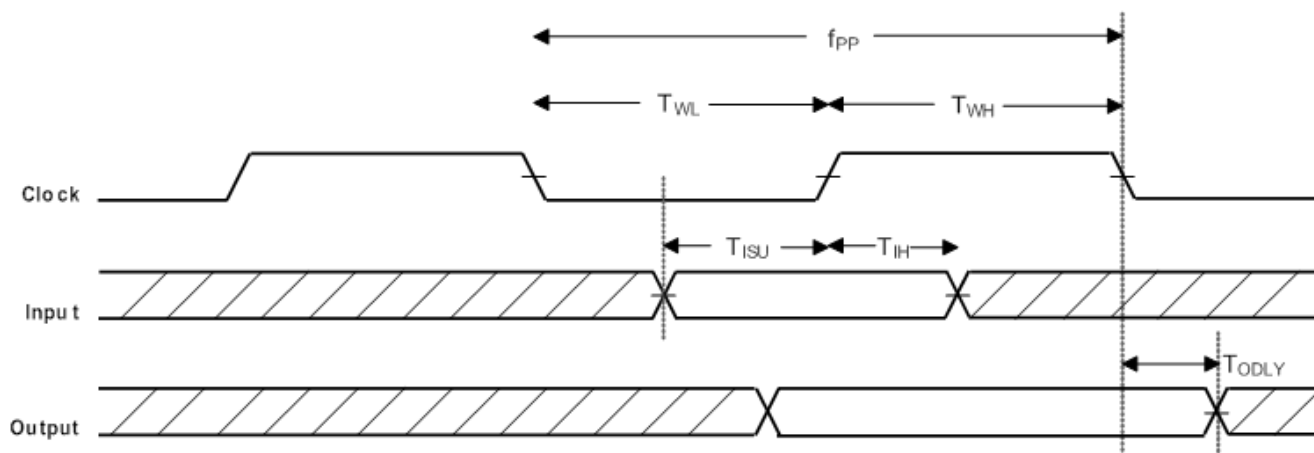
Allows card to interrupt host

3-1-1. SDIO Interface Signal Description

Pin Name	Signal Name	Type	Description
SD_CLK	CLK	I/O	SDIO 1-bit mode: Clock SDIO SPI mode: Clock
SD_CMD	CMD	I/O	SDIO 1-bit mode: Command line SDIO SPI mode: Data input
SD_DAT[3]	DAT3	I/O	SDIO 4-bit mode: Data line bit [3] SDIO 1-bit mode: Not used SDIO SPI mode: Chip select (active low)
SD_DAT[2]	DAT2	I/O	SDIO 4-bit mode: Data line bit [2] or Read Wait (optional) SDIO 1-bit mode: Read Wait (optional) SDIO SPI mode: Reserved
SD_DAT[1]	DAT1	I/O	SDIO 4-bit mode: Data line bit [1] SDIO 1-bit mode: Interrupt SDIO SPI mode: Interrupt
SD_DAT[0]	DAT0	I/O	SDIO 4-bit mode: Data line bit [0] SDIO 1-bit mode: Data line SDIO SPI mode: Data output

3-1-2. Default Speed, High Speed Modes (3.3V)

SDIO Protocol Timing Diagram – Default Speed Mode (3.3V)



SDIO Protocol Timing Diagram – HighSpeed Mode (3.3V)

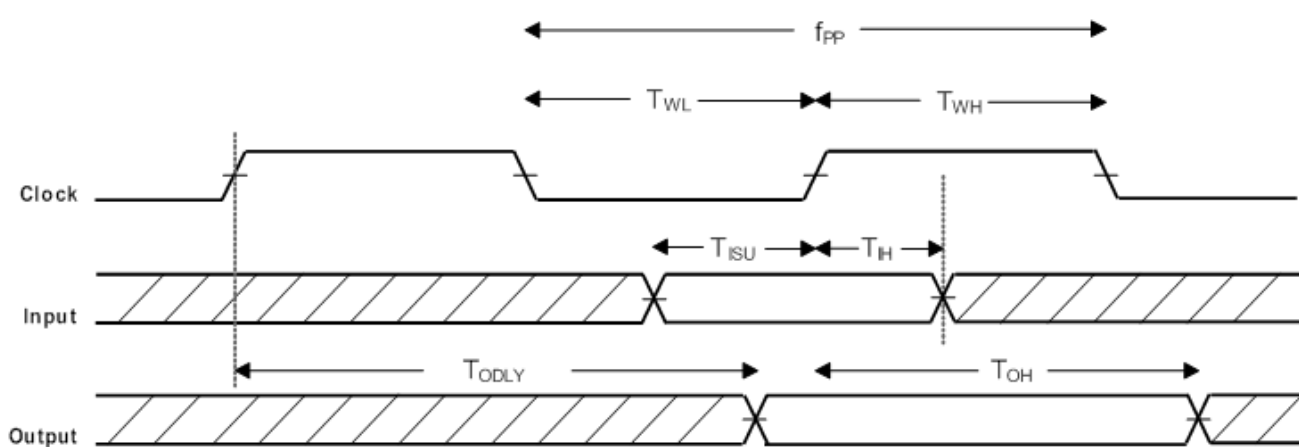


Table shows SDIO Timing Data—Default Speed, High Speed Modes (3.3V)

NOTE: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f _{PP}	Clock Frequency	Default Speed	0	--	25	MHz
		High Speed	0	--	50	MHz
T _{WL}	Clock Low Time	Default Speed	10	--	--	ns
		High Speed	7	--	--	ns
T _{WH}	Clock High Time	Default Speed	10	--	--	ns
		High Speed	7	--	--	ns
T _{ISU}	Input Setup Time	Default Speed	5	--	--	ns
		High Speed	6	--	--	ns
T _{IH}	Input Hold Time	Default Speed	5	--	--	ns
		High Speed	2	--	--	ns
T _{ODLY}	Output Delay Time CL ≤ 40 pF (1 card)	Default Speed	--	--	14	ns
		High Speed	---	-1	4	ns
T _{OH}	Output Hold Time	High Speed	2.5	--	--	ns

3-1-3. SDR12, SDR25, SDR50 Modes (up to 100MHz) (1.8V)

SDIO Protocol Timing Diagram – SDR12,SDR25,SDR50 Modes (up to 100MHz) (1.8V)

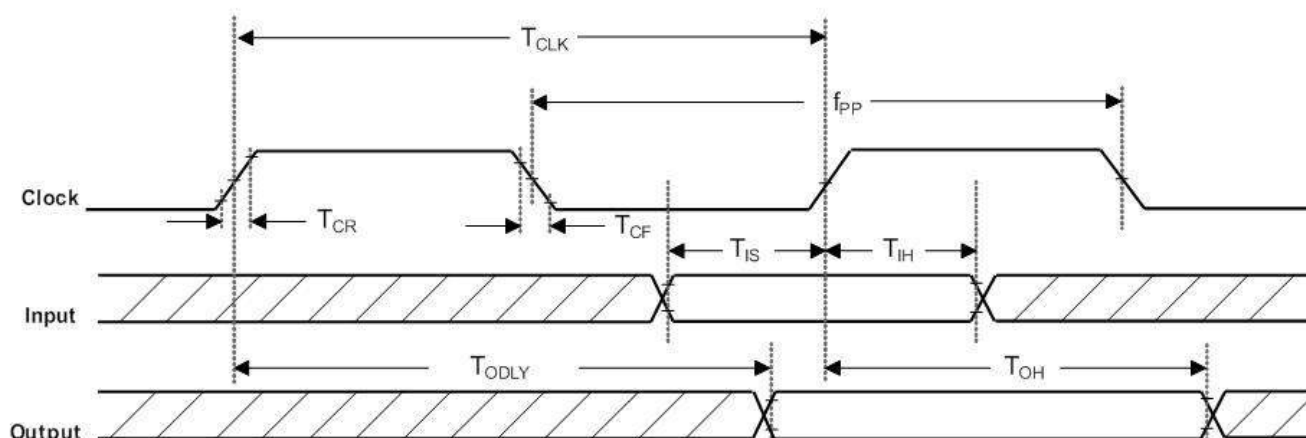


Table shows SDIO Timing Data—SDR12,SDR25,SDR50 Modes (up to 100MHz) (1.8V)

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{PP}	Clock frequency	SDR12/25/50	25	--	100	MHz
T_{IS}	Input setup time	SDR12/25/50	3	--	--	ns
T_{IH}	Input hold time	SDR12/25/50	0.8	--	--	ns
T_{CLK}	Clock time	SDR12/25/50	10	--	40	ns
T_{CR}, T_{CF}	Rise time, fall time $T_{CR}, T_{CF} < 2$ ns (max) at 100 MHz $C_{CARD} = 10$ pF	SDR12/25/50	--	--	$0.2 \cdot T_{CLK}$	ns
T_{ODLY}	Output delay time $C_L \leq 30$ pF	SDR12/25/50	--	--	7.5	ns
T_{OH}	Output hold time $C_L = 15$ pF	SDR12/25/50	1.5	--	--	ns

3-1-4. SDR104 Modes (208MHz) (1.8V)

SDIO Protocol Timing Diagram –SDR104 Mode (208MHz)

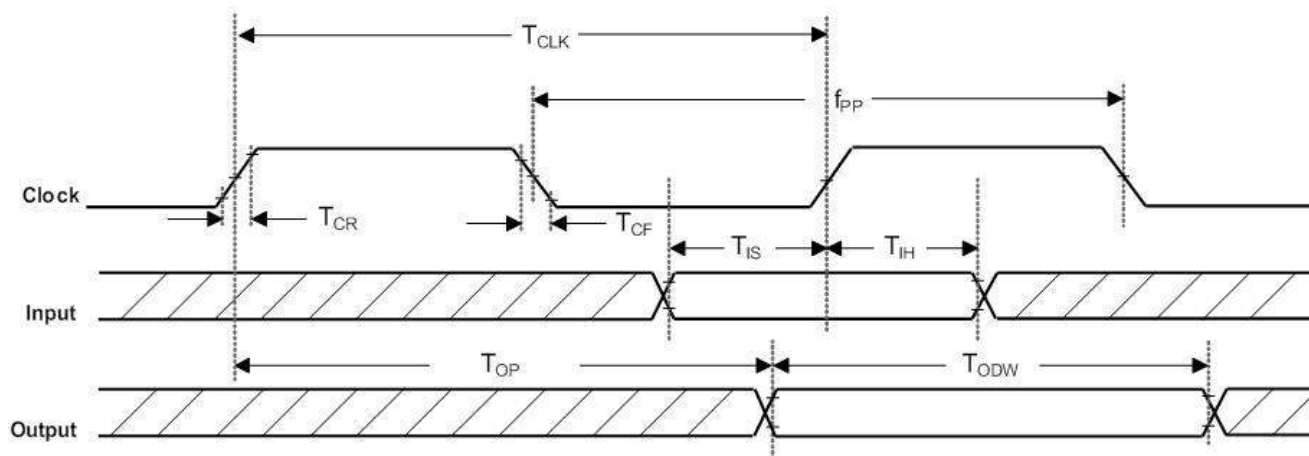


Table shows SDIO Timing Data—SDR104 Mode (208MHz)

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{PP}	Clock frequency	SDR104	0	--	208	MHz
T_{IS}	Input setup time	SDR104	1.4	--	--	ns
T_{IH}	Input hold time	SDR104	0.8	--	--	ns
T_{CLK}	Clock time	SDR104	4.8	--	--	ns
T_{CR}, T_{CF}	Rise time, fall time $T_{CR}, T_{CF} < 0.96$ ns (max) at 208 MHz $C_{CARD} = 10$ pF	SDR104	--	--	$0.2 \cdot T_{CLK}$	ns
T_{OP}	Card output phase	SDR104	0	--	10	ns
T_{ODW}	Output timing of variable data window	SDR104	2.88	--	--	ns

3-1. PCI Express Interface

3-1-1 Differential Tx Output Electricals

Sy mbol	Parame te r	Min	Typ	Max	Unit s
UI	Unit interval Each UI is 400 ps \pm 300 PPM. UI does not account for SSC dictated variations.	399.98	400	400.12	ps
V _{Tx_DIFFpp}	Differential peak-to-peak output voltage $V_{Tx_DIFFpp} = 2 * V_{Tx_D+} - V_{Tx_D-} $	0.800	--	1.2	V
V _{Tx_DE_RATIO}	De-emphasized differential output voltage (ratio)	-3.0	-3.5	-4.0	db
T _{Rx_EYE}	Minimum Tx eye wid th	0.75	--	--	UI
T _{Rx_EYE_MEDIAN_MAX_JIT}	Maximum time between jitter median and maximum deviation from median	--	--	0.125	UI
T _{Tx_RISE} , T _{Tx_FALL}	D+/D- Tx output rise/fall time	0.125	--	--	UI
V _{Tx_CM_DC_ACTIV E_IDLE_DELTA}	Absolute delta of DC common mode voltage during L0 and electrical idle	0-	-	100	mV
V _{Tx_CM_DC_LINE_DELTA}	Absolute delta of DC common mode voltage between D+ and D-	0-	-	25	mV
V _{Tx_IDLE_DIFFp}	Electrical idle differential peak output voltage	0	--	20	mV
V _{Tx_RCV_DETECT}	Voltage change allowed during receiver detection	--	--	600	mV
V _{Tx_DC_CM}	Tx DC common mode voltage	--	--	3.6	V
I _{Tx_SHORT}	Tx short circuit current limit	--	--	90	mA
T _{Tx_IDLE_MIN}	Minimum time spent in electrical idle	50	--	--	UI
T _{Tx_IDLE_SET_TO_IDLE}	Maximum time to transition to a valid electrical idle after sending an electrical idle ordered set	--	--	20	UI
T _{Tx_IDLE_TO_DIFF_DATA}	Maximum time to transition to valid Tx specifications after leaving an electrical idle condition	--	--	20	UI
RL _{Tx_DIFF}	Differential return loss	10	--	--	dB
RL _{Tx_CM}	Common mode return loss	6	--	--	dB
C _{Tx}	AC coupling capacitor	75	--	200	nF
T _{Crosstalk}	Crosstalk random timeout	0	--	1	ms

3-1-2 Differential Rx Output Electricals

Symbol	Parameter	Min	Typ	Max	Unit s
UI	Unit interval Each UI is 400 ps \pm 300 ppm. UI does not account for SSC dictated variations.	399.98	400	400.12	ps
V_{Rx_DIFFpp}	Differential peak-to-peak voltage $V_{Rx_DIFFpp} = 2 * V_{Rx_D+} - V_{Rx_D-} $	0.175	--	1.2	V
T_{Rx_EYE}	Minimum receiver eye width	0.4	--	--	UI
$T_{Rx_EYE_MEDIAN_MAX_JIT}$	Maximum time between jitter median and maximum deviation from median	--	--	0.3	UI
$V_{Rx_CM_ACp}$	AC peak common mode input voltage	--	--	150	mV
RL_{Rx_DIFF}	Differential return loss	10	--	--	dB
RL_{Rx_CM}	Common mode return loss	6	--	--	dB
$Z_{Rx_DIFF_DC}$	DC differential input impedance	80	100	120	Ω
Z_{Rx_DC}	DC input impedance	40	50	60	Ω
$Z_{Rx_HIGH_IMP_DC_POS}$	Powered down DC input impedance positive	50	--	--	k
$Z_{Rx_HIGH_IMP_DC_NEG}$	Powered down DC input impedance negative	1	--	--	k Ω
$V_{Rx_IDLE_DET_DIFFpp}$	Electrical idle detect threshold	65	--	175	mV
$T_{Rx_IDLE_DET_DIFF_ENTERTIME}$	Unexpected electrical idle enter detect threshold integration time	--	--	10	ms
L_{Rx_SKEW}	Total skew	---	-2	0	ns

3-2. USB Interface

The USB device interface is compliant with the Universal Serial Bus Specification, Revision 2.0, April 27, 2000. A USB host uses the USB cable bus and the USB 2.0 device interface to communicate with the chip.

The main features of the USB device interface include:

High/full speed operation (480/12 Mbps)

Suspend/host resume/device resume (remote wake-up)

Built-in DMA engine that reduces interrupt loads on the embedded processor and reduces the system bus bandwidth requirement for serving the USB device operation

The USB 2.0 device interface is designed with 3.3V signal level pads.

3-2-1. USB 2.0 Device Interface Description

Table shows the signal mapping between the AW-CM276NF and the USB Specification, Revision 2.0.

Pin Name	USB 2.0 Specification Pin Name	Description
Pin72/ 3V3_USB	VBUS	USB Bus Power Supply On-board regulator regulates voltage from VBUS level to voltage levels used by USB PHY.
	GND	USB Bus Ground Common ground on SoC device.
Pin70/ USB_DP	D+	USB Bus Data Positive. One of the differential data pair.
Pin69/ USB_DN	D-	USB Bus Data Negative. One of the differential data pair.

3-2-2. USB 2.0 Device Functional Description

The device controller uses internal Scatter/Gather DMA engine to transfer the transmit packet from internal SRAM to USB and the receive packet from USB to internal SRAM. The Device IN Endpoint DMA (DIEPDMA_n) and Device OUT Endpoint DMA (DOEPDMA_n) registers are used by the DMA engine to access the base descriptor. The application is interrupted after the programmed transfer size extracted from the descriptors is transmitted or received. By using registers, interrupts, and special data structures, the device controller can communicate with the device controller driver (application/software) about bus states, host request, and data transfer status. The device controller driver also has all of the routines to respond to the device framework commands issued by a USB host, so it controls the attachment, configuration, operation, and detachment of the device.

3-3. High-Speed UART Interface

The AW-CM276NF supports a high-speed Universal Asynchronous Receiver/Transmitter (UART) interface, compliant to the industry standard 16550 specification. High-speed baud rates are supported to provide the physical transport between the device and the host for exchanging Bluetooth data. Table shows the rates supported.

The UART interface features include:

- FIFO mode permanently selected for transmit and receive operations
- Two pins for transmit and receive operations
- Two flow control pins

Interrupt triggers for low-power, high throughput operation

The UART interface operation includes:

- Upload boot code to the internal CPU (for debug purposes)
- Support diagnostic tests
- Support data input/output operations for peripheral devices connected through a standard UART interface

UART Baud Rates Supported

Baud Rate				
1200	38400	460800	1500000	3000000
2400	57600	500000	1843200	3250000
4800	76800	921600	2000000	3692300
9600	115200	1000000	2100000	4000000
19200	230400	1382400	2764800	--

3-3-1. UART Interface Signal Description

Table shows the standard UART signal names on the device.

Signal Name	16550 Standard Pin Name	Description
Data Bus		
UART_SIN	SIN	Serial data input from modem, data set, or peripheral device
UART_SOUT	SOUT	Serial data output from modem, data set, or peripheral device
Modem Control		
UART_RTSEN	RTS	Request To Send output to modem, data set, or peripheral device (active low)
UART_CTSEN	CTS	Clear To Send input from modem, data set, or peripheral device (active low)

3-3-2. UART Interface Functional Description

3-3-2-1. Booting from UART

When booting from the UART, the AW-CM276NF device has the following requirements:

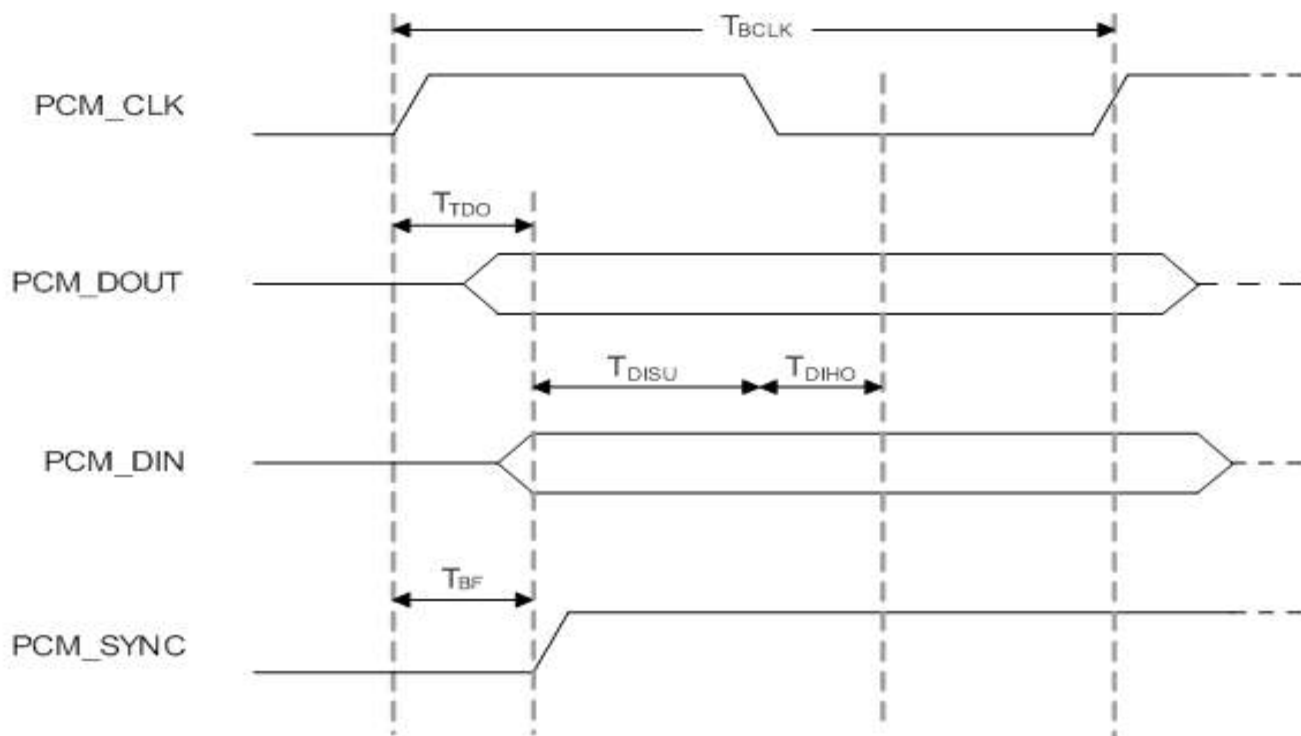
System Requirement	Description
Number of data bits	8 bits
Stop bits	1 bit
Parity	No parity
Baud Rate	115200

3-3-2-2. UART as Test Port

Test diagnostic programs may be uploaded to the CPU through the UART interface. During execution, the diagnostic program transmits performance and status information through the UART by performing a write to the PBU address space designated to the UART.

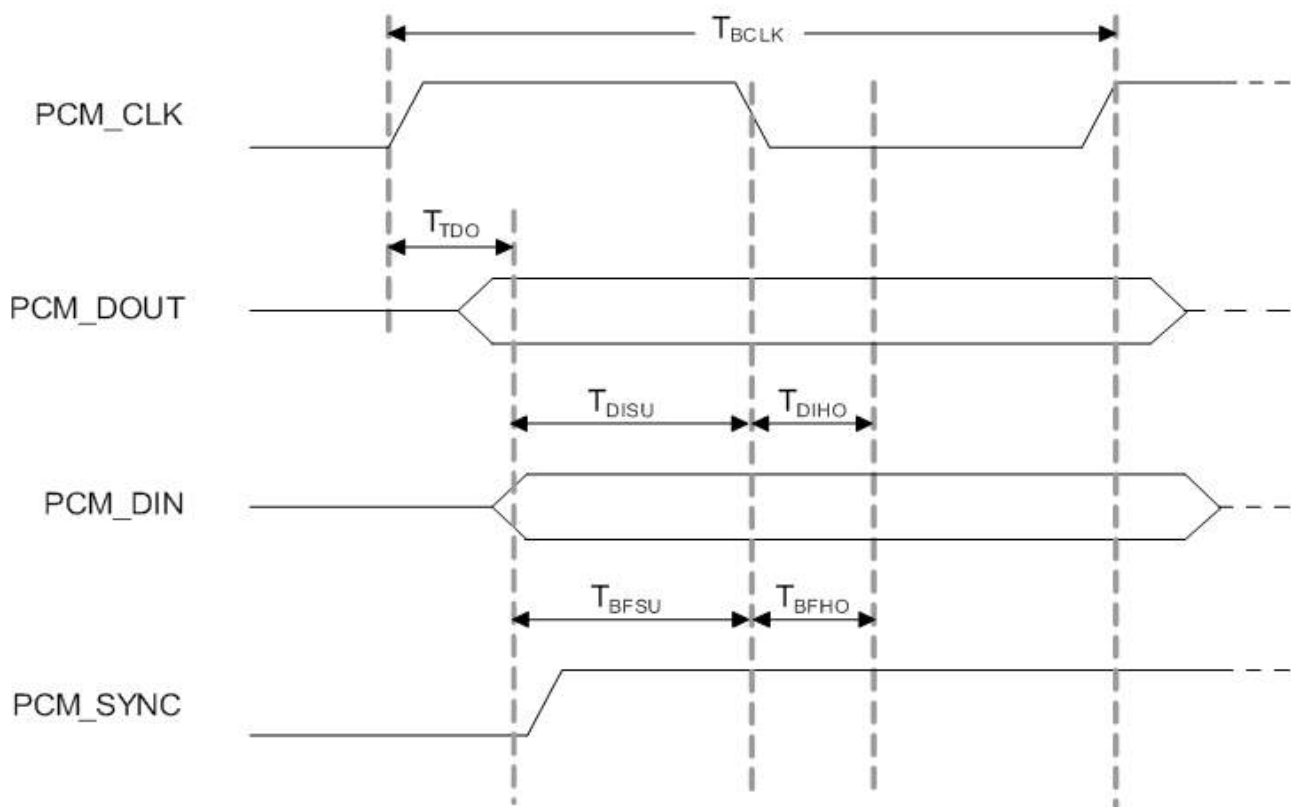
3-4. PCM Interface

3-4-1. PCM Timing Specification – Master Mode



Sy mbol	Parameter	Con dition	Min	Typ	Max	Unit s
F_{BCLK}	--	--	--	2/2.048	--	MHz
Duty Cycle _{BCLK}	--	--	0.4	0.5	0.6	--
T_{BCLK} rise/fall	--	--	--	3	--	ns
T_{DO}	--	--	--	--	15	ns
T_{DISU}	--	--	20	--	--	ns
T_{DIHO}	--	--	15	--	--	ns
T_{BF}	--	--	--	--	15	ns

3-4-2. PCM Timing Specification – Slave Mode



Symbol	Parameter	Condition	Min	Typ	Max	Unit
F_{BCLK}	--	--	--	2/2.048	--	MHz
Duty Cycle _{BCLK}	--	--	0.4	0.5	0.6	--
$T_{BCLK \text{ rise/fall}}$	--	--	--	3	--	ns
T_{DO}	--	--	--	--	30	ns
T_{DISU}	--	--	15	--	--	ns
T_{DIHO}	--	--	10	--	--	ns
T_{BFSU}	--	--	15	--	--	ns
T_{BFHO}	--	--	10	--	--	ns

4. Pin Definition

Pin No	Definition	Basic Description	Type	Supply
1	NC	NC		
2	NC	NC		
3	NC	NC		
4	3.3V	3.3V Power Supply	I	3.3V
5	3.3V	3.3V Power Supply	I	3.3V
6	GND	System Ground Pin		
7	NC	NC		
8	CONFIG_HOST[0]	Configuration: CONFIG_HOST[0]		
9	CONFIG_HOST[1]	Configuration: CONFIG_HOST[1]		
10	CONFIG_HOST[2]	Configuration: CONFIG_HOST[2]		
11	GPIO[17] /UART_LTE_SOUT/TDO	GPIO[17] / UART_LTE_SOUT/TDO (output)	O	VIO
12	GPIO[16] /UART_LTE_SIN/TDI	GPIO[16] / UART_LTE_SIN/TDI (input)	I	VIO
13	CONFIG_HOST[3]	Configuration: CONFIG_HOST[3]		
14	NC	NC		
15	GPIO[1]	GPIO[1] (input/output)	I/O	VIO
16	NC	NC	I/O	
17	GND	System Ground Pin		
18	GPIO[25]	GPIO[25] (input/output)	I/O	VIO
19	NC	NC		
20	GND	System Ground Pin		
21	GPIO[26]	GPIO[26] (input/output)	I/O	VIO
22	GPIO[27]	GPIO[27] (input/output)	I/O	VIO
23	GND	System Ground Pin		
24	ATEST0	NC, reserved for debug	I	
25	NC	NC	I/O	
26	GND	System Ground Pin		
27	SLP_CLK	Sleep Clock Input Used for WLAN and Bluetooth low-power modes. External sleep clock of 32.768 KHz must be used for auto reference clock calibration and for WLAN/Bluetooth low power operation.	I	

Pin No	Definition	Basic Description	Type	Supply
28	GPIO[13]/BT IRQ(O)	GPIO[13]/ BT Wake Host(active low) (output)	O	VIO
29	PCIE_WAKEn	PCIe wake signal (input/output) (active low)	I/O	VIO
30	PCIE_CLKREQn	PCIe clock request (input/output) (active low)	I/O	VIO
31	GPIO[21]/PCIE_PERSTn	PCIe host indication to reset the device (input) (active low)	I	VIO
32	GND	System Ground Pin		
33	PCIE_RCLK_N	PCI Express Differential Clock Input—Negative	I	1.8V(internal)
34	PCIE_RCLK_P	PCI Express Differential Clock Input—Positive	I	1.8V(internal)
35	GND	System Ground Pin		
36	PCIE_TX_N/USB3.0_TX_N	PCI Express Transmit Data—Negative / USB 3.0 TX negative	O	1.8V(internal)
37	PCIE_TX_P/USB3.0_TX_P	PCI Express Transmit Data—Positive / USB 3.0 TX positive	O	1.8V(internal)
38	GND	System Ground Pin		
39	PCIE_RX_N/USB3.0_RX_N	PCI Express Receive Data—Negative / USB 3.0 RX negative	I	1.8V(internal)
40	PCIE_RX_P/USB3.0_RX_P	PCI Express Receive Data—Positive / USB 3.0 RX positive	I	1.8V(internal)
41	GND	System Ground Pin		
42	GPIO[0]/CLK_REQ	GPIO[0] (input/output)	O	VIO
43	NC	NC		
44	VIO_SD	1.8V/3.3V Digital I/O SDIO Power Supply	I	VIO_SD
45	PDn	Full Power Down (input) (active low)	I	3.3V
46	GPIO[14] /TCK/WLAN Wake Host	GPIO[14]/TCK/WLAN Wake Host(active low) (output)	O	VIO
47	SD_DAT[3]	SDIO Data line Bit[3]	I/O	VIO_SD
48	SD_DAT[2]	SDIO Data line Bit[2]	I/O	VIO_SD
49	SD_DAT[1]	SDIO Data line Bit[1]	I/O	VIO_SD
50	SD_DAT[0]	SDIO Data line Bit[0]	I/O	VIO_SD
51	SD_CMD	SDIO Command/response (input/output)	I/O	VIO_SD
52	SD_CLK	SDIO Clock input	I	VIO_SD
53	GPIO[12] / UART Host Wake BT	GPIO[12]/ UART Host Wake BT(active low) (input)	I	VIO
54	GPIO[10] / UART_CTSn	GPIO[10 / UART_CTSn] (input)	I	VIO
55	GPIO[8] / UART_SOUT	GPIO[8] / UART_SOUT (output)	O	VIO
56	GPIO[9] / UART_SIN	GPIO[9] / UART_SIN (input)	I	VIO
57	GPIO[11] / UART_RTSn	GPIO[11] / UART_RTSn (output)	O	VIO
58	GPIO[7] / PCM_SYNC	GPIO[7] / PCM_SYNC (input/output)	I/O	VIO

Pin No	Definition	Basic Description	Type	Supply
59	GPIO[4] / PCM_IN	GPIO[4] / PCM_IN (input)	I	VIO
60	GPIO[5] / PCM_OUT	GPIO[5] / PCM_OUT (output)	O	VIO
61	GPIO[6] / PCM_CLK	GPIO[6] / PCM_CLK (input)	I	VIO
62	GND	System Ground Pin		
63	GPIO[22] / PCIE_W_DISABLEn	GPIO[22] / PCIE_W_DISABLEn (input)	I	VIO
64	GPIO[2] / WLAN_LED	LED_OUT_WLAN (output)	O	VIO
65	GPIO[3] / BT_LED	LED_OUT_BT (output)	O	VIO
66	GPIO[15] / TMS/ Host Wake WLAN	GPIO[15] / JTAG TMS/ Host Wake WLAN (input)	I	VIO
67	NC	NC		
68	GND	System Ground Pin		
69	USB_DM	USB Serial Differential Data Minus	I/O	3.3V
70	USB_DP	USB Serial Differential Data Plus	I/O	3.3V
71	GND	System Ground Pin		
72	3.3V	3.3V Power Supply	I	3.3V
73	VIO	Digital I/O Power Supply	I	VIO
74	GND	System Ground Pin		
75	GND	System Ground Pin		
76	GND	System Ground Pin		
77	GND	System Ground Pin		
78	GND	System Ground Pin		
79	GND	System Ground Pin		
80	GND	System Ground Pin		
81	GND	System Ground Pin		
82	GND	System Ground Pin		
83	GND	System Ground Pin		
84	GND	System Ground Pin		
85	GND	System Ground Pin		
86	GND	System Ground Pin		
87	GND	System Ground Pin		
88	GND	System Ground Pin		
89	GND	System Ground Pin		

Pin No	Definition	Basic Description	Type	Supply
90	GND	System Ground Pin		
91	GND	System Ground Pin		
92	GND	System Ground Pin		
93	GND	System Ground Pin		
94	GND	System Ground Pin		
95	GND	System Ground Pin		
96	GND	System Ground Pin		
G1	GND	System Ground Pin		
G2	GND	System Ground Pin		
G3	GND	System Ground Pin		
G4	GND	System Ground Pin		
G5	GND	System Ground Pin		
G6	GND	System Ground Pin		
G7	GND	System Ground Pin		
G8	GND	System Ground Pin		
G9	GND	System Ground Pin		
G10	GND	System Ground Pin		
G11	GND	System Ground Pin		
G12	GND	System Ground Pin		
G13	GND	System Ground Pin		
G14	GND	System Ground Pin		
G15	GND	System Ground Pin		
G16	GND	System Ground Pin		
G19	GND	System Ground Pin		
G20	GND	System Ground Pin		
G21	GND	System Ground Pin		
G22	GND	System Ground Pin		
G23	GND	System Ground Pin		
G24	GND	System Ground Pin		
G25	GND	System Ground Pin		

Pin No	Definition	Basic Description	Type	
G26	GND	System Ground Pin		
G27	GND	System Ground Pin		
G28	GND	System Ground Pin		
G29	GND	System Ground Pin		
G30	GND	System Ground Pin		
G31	GND	System Ground Pin		
G32	GND	System Ground Pin		
G33	GND	System Ground Pin		
G34	GND	System Ground Pin		
G35	GND	System Ground Pin		
G36	GND	System Ground Pin		

Notes:

1. PCIE Impedance targets: Single-ended Z of 60 ohms +- 15% . Differential Impedance of ~100 ohm +- 20%.
2. USB Impedance targets: D+/D- are differential and should have 90ohms impedance.
3. * Implement by different hardware version.

Note: Interface supports and combinations as shown below:

Scenario	WLAN	BT	Strap value CON[2:0]
1	SDIO	UART	000
2	SDIO	SDIO	001
3	PCIe	USB	010(default)
4	PCIe	UART	011
5	USB3.0	UART	100
6	USB2.0	USB2.0	101
7	USB3/2.0	USB3/2.0	110
8	USB3.0	USB3.0	111

*Configuration pins:

Pin No.	Configuration
10	CON[2]
9	CON[1]
8	CON[0]

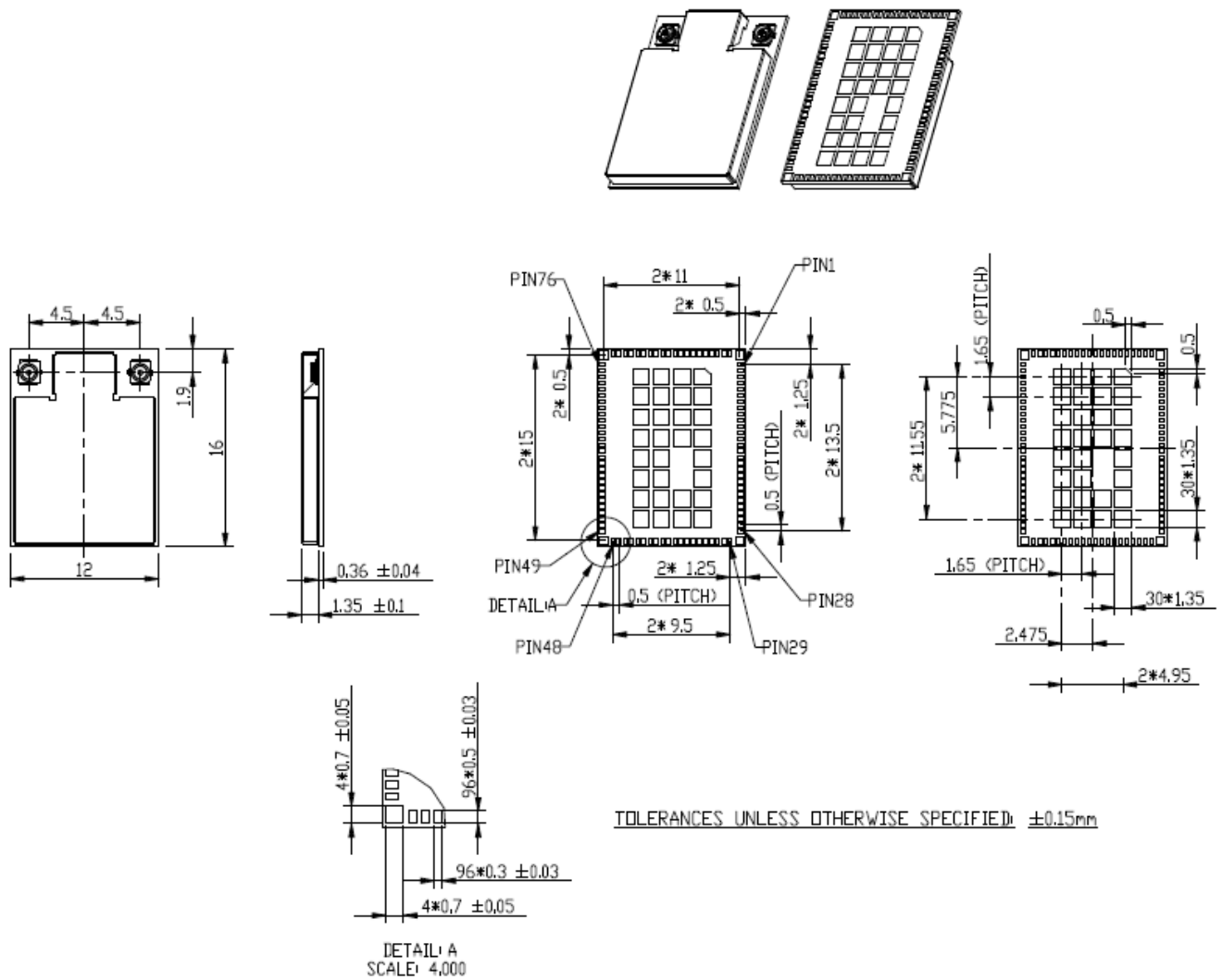
5. Pin map

AW-CM276NF Top View Pin Map

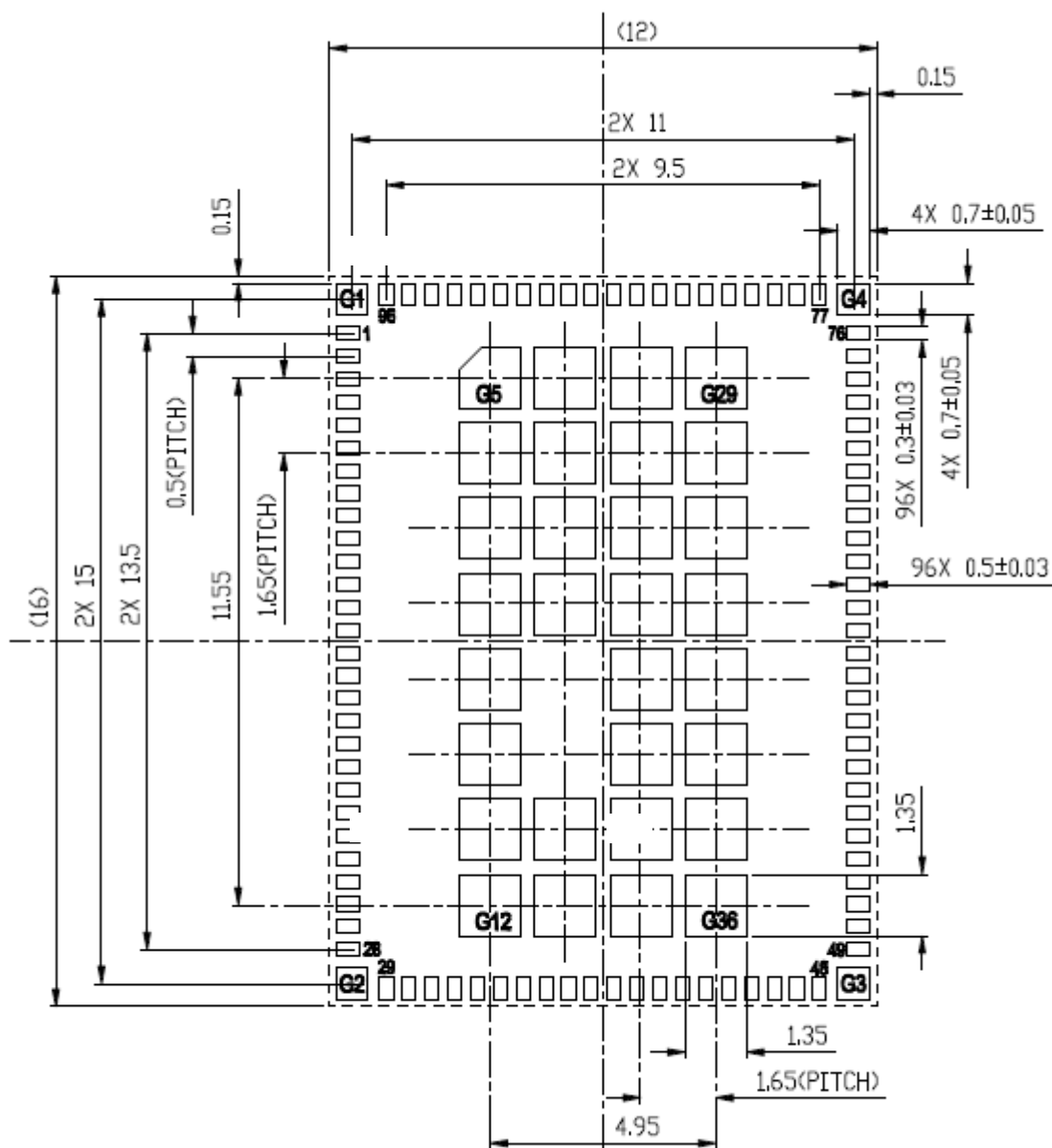
	96	95	94	93	92	91	90	89	88	87	86	85	84	83	82	81	80	79	78	77		
	GND(G1)	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND(G4)	
1	NC																				GND	76
2	NC																				GND	75
3	NC																				GND	74
4	3.3V			GND(G5)			GND(G13)					GND(G21)				GND(G29)					VIO	73
5	3.3V																				3.3V	72
6	GND																				GND	71
7	NC			GND(G6)			GND(G14)					GND(G22)				GND(G30)					USB_DP	70
8	CONFIG_HOST[0]																				USB_DM	69
9	CONFIG_HOST[1]																				GND	68
10	CONFIG_HOST[2]																				NC	67
11	GPIO[17]UART_LTE_SOUT/TDO			GND(G7)			GND(G15)					GND(G23)				GND(G31)					GPIO[15]TMS/Host Wake WLAN	66
12	GPIO[16]UART_LTE_SIN/TDI																				GPIO[3]BT_LED	65
13	CONFIG_HOST[3]																				GPIO[2]WLAN_LED	64
14	NC			GND(G8)			GND(G16)					GND(G24)				GND(G32)					GPIO[22]PCIE_W_DISABLEn	63
15	GPIO[1]																				GND	62
16	NC																				GPIO[6]PCM_CLK	61
17	GND																				GPIO[5]PCM_OUT	60
18	GPIO[25]			GND(G9)								GND(G25)				GND(G33)					GPIO[4]PCM_IN	59
19	NC																				GPIO[7]PCM_SYNC	58
20	GND																				GPIO[11]UART_RTSn	57
21	GPIO[26]			GND(G10)								GND(G26)				GND(G34)					GPIO[9]UART_SIN	56
22	GPIO[27]																				GPIO[8]UART_SOUT	55
23	GND																				GPIO[10]UART_CTSn	54
24	ATEST0			GND(G11)			GND(G19)					GND(G27)				GND(G35)					GPIO[12]UARTHostWakeBT	53
25	NC																				SD_CLK	52
26	GND																				SD_CMD	51
27	SLP_CLK			GND(G12)			GND(G20)					GND(G28)				GND(G36)					SD_DAT[0]	50
28	GPIO[13]BT_IRQ(O)																				SD_DAT[1]	49
	GND(G2)	PCIE_WAKEn	PCIE_CLKREQn	GPIO[21]/ PCIE_PERSTn	GND	PCIE_RCLK_N	PCIE_RCLK_P	GND	PCIE_TX_N/ USB3.0_TX_N	PCIE_TX_P/ USB3.0_TX_P	GND	PCIE_RX_N/ USB3.0_RX_N	PCIE_RX_P/ USB3.0_RX_P	GND	GPIO[0]/ CLK_REQ	NC	VIO_SD	PDn	GPIO[14]TCK/ WLAN Wake Host	SD_DAT[3]	SD_DAT[2]	GND(G3)
		29	30	31	32	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48	

6. Mechanical Information

6-1. Package Outline Drawing

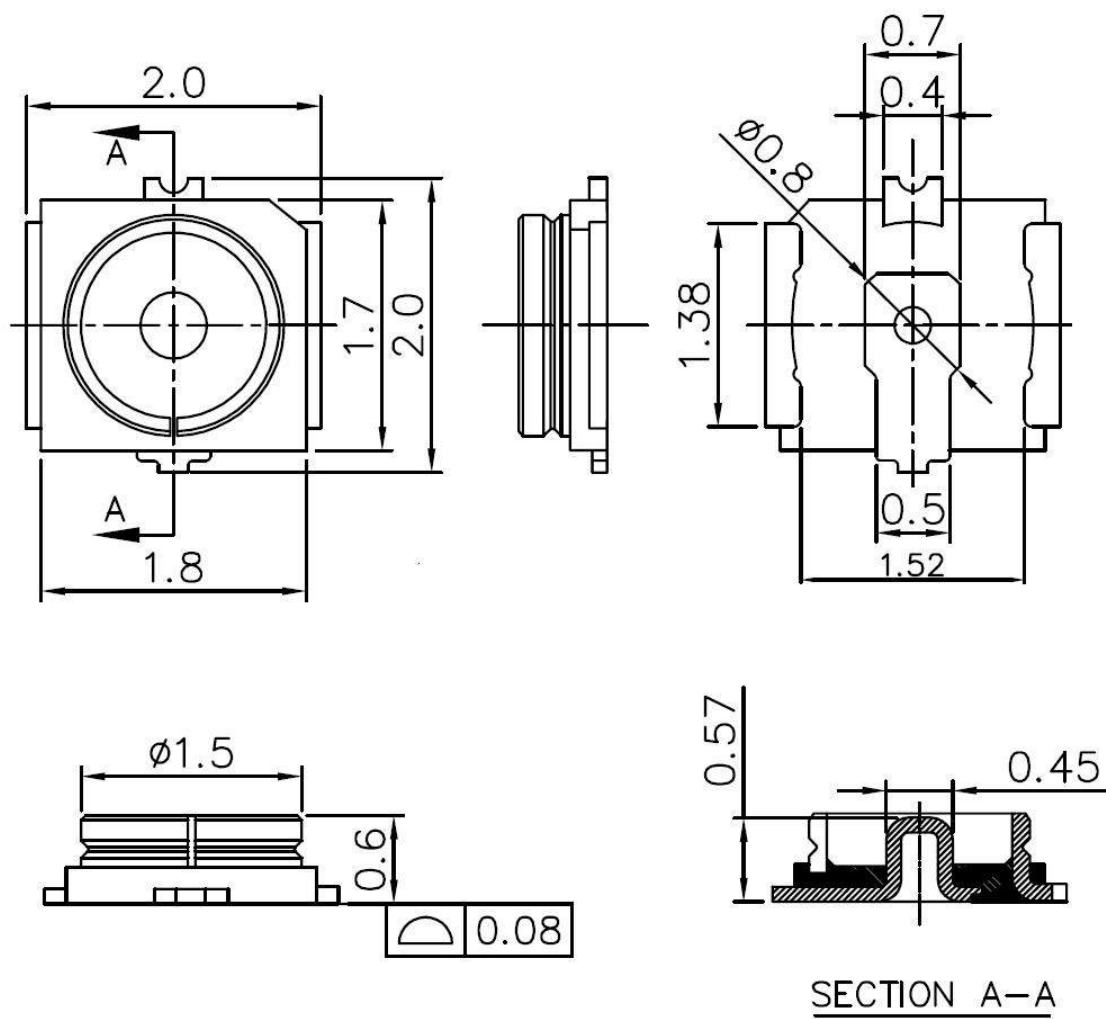


6-2. Pin out drawing



RECOMMENDED SOLDER PAD LAYOUT

6-3. Antenna Connector Drawing



UNITS: mm

FCC Statement

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

(1) This device may not cause harmful interference.

(2) This device must accept any interference received, including interference that may cause undesired operation.

2. Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Note: This equipment has been tested and found to comply with the limits for a class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This equipment should be installed and operated with a minimum distance of 20 cm between the radiator and your body

Operations in the 5.15-5.25GHz band are restricted to indoors usage only.

ISED Statement

This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the following two conditions:

This device may not cause interference.

This device must accept any interference, including interference that may cause undesired operation of the device.

This equipment should be installed and operated with a minimum distance of 20 cm between the radiator and your body

Operations in the 5.15-5.25GHz band are restricted to indoors usage only.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Cet équipement doit être installé et utilisé avec une distance minimale de 20 cm entre le radiateur et votre corps

Le fonctionnement dans la bande 5,15 - 5,25 GHz est limité à un usage intérieur.

The Module is designed to comply with the FCC statement. FCC ID is 2BBEG-HFX8AMC. The host system using Module, should have label indicated it contain modular's FCC ID: 2BBEG-HFX8AMC. This radio module must not installed to colocate and operating simultaneously with other radios in host system additional testing and equipment authorization may be required to operating simultaneously with other radio.

The Module and its antenna must not be co-located or operating in conjunction with any other transmitter or antenna within a host device.

The modular must be installed in the host that assign by Company name: HAI ROBOTICS Co., Ltd., Model no.: HFX8A_MC1 if other host types used would need further evaluation and possible C2PC if they are not significantly similar to the one tested The WIFI Module is designed for a compact PCB design. It should be installed and operated with host or other minimum distance of 20 centimeters between the radiator and your body." To comply with FCC regulations limiting both maximum RF output power and human exposure to RF radiation, the maximum antenna gain including cable loss in a mobile-only exposure condition must not exceed 4.97dBi in the 5G band. The module uses IPEX antenna interface and ping angle interface antenna, this antenna is sold with the module.

Notice to OEM integrator

The end user manual shall include all required regulatory information/warning as show in this manual. The OEM integrator is responsible for testing their end-product for any additional compliance requirements required with this module installed. If the final product contains circuits of other FCC PART 15 Subparts, the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed The intended use is generally not for the general public. It is generally for industry/commercial use. The connector is within the transmitter enclosure and can only be accessed by disassembly of the transmitter that is not nomally required, the user has no access to the connector. Installation must be controlled. Installation requires special training.

This device complies with Part 15 of the FCC Rules.

This equipment should be installed and operated with a minimum distance of 20 cm between the radiator and your body

Operations in the 5.15-5.35GHz band are restricted to indoors usage only.